



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

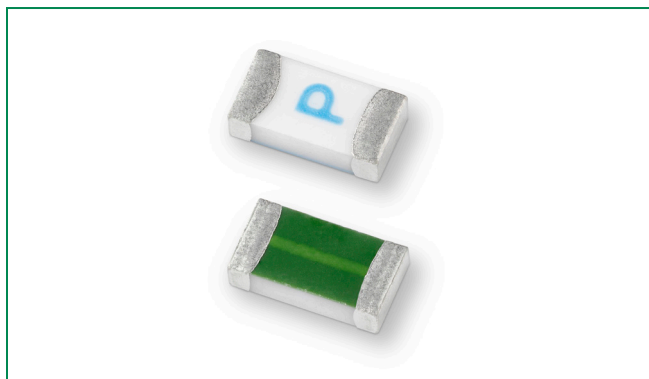
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440A Series, 1206 High I²t Fuse



Agency Approvals

AGENCY	AGENCY FILE NUMBER	AMPERE RANGE
	E10480	0.500A - 8A
	29862	0.500A - 8A

Electrical Characteristics for Series

% of Ampere Rating	Ampere Rating	Opening Time at 25°C
100%	.50A - .75A 1.75A - 8A	4 hours, Minimum
350%	.50A - .75A 1.75A - 8A	5 secs., Maximum

Description

The 440A Series AECQ-Compliant fuses are specifically tested to cater to secondary circuit protection needs of compact auto electronics applications.

The general design ensures excellent temperature stability and performance reliability. This high I²t fuse series is designed to have ultra high inrush current withstand capability to avoid nuisance fuse open.

Features

- Operating Temperature from -55°C to +150°C
- 100% Lead-free, RoHS compliant and Halogen-free
- Meets Littelfuse's automotive qualifications*
- Ultra high I²t values
- Fast response to faulty current to ensure over-current protection to sensitive electronic component

* - Largely based on Littelfuse internal AEC-Q200 test plan.

Applications

- Li-ion Battery
- LED Lighting
- Automotive Navigation System
- TFT Display
- Battery Management System (BMS)
- Cluster

Additional Information



Datasheet





Resources



Samples

Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max. Voltage Rating (V)	Interrupting Rating (AC/DC) ¹	Nominal Resistance (Ohms) ²	Nominal Melting I ² t (A ² Sec.) ³	Nominal Voltage Drop At Rated Current (V) ⁴	Nominal Power Dissipation At Rated Current (W)	Agency Approvals	
									
0.5	.500	63	50A @ 63VAC/DC	0.8140	0.02642	0.4831	0.242	x	X
0.75	.750	63		0.4624	0.09312	0.3983	0.299	x	X
1.75	1.75	32		0.0450	0.3312	0.0777	0.136	x	X
2	002.	32		0.0385	0.4326	0.0792	0.158	x	X
2.5	02.5	32	50A @ 32VAC/DC	0.02850	0.8191	0.0747	0.187	x	X
3	003.	32		0.02252	1.232	0.0742	0.223	x	X
3.5	03.5	32		0.01845	1.789	0.0757	0.265	x	X
4	004.	32		0.01553	2.601	0.0709	0.284	x	X
5	005.	32		0.0120	4.761	0.0654	0.327	x	X
7	007.	32		0.00753	8.464	0.0696	0.487	x	X
8	008.	32		0.00634	12.95	0.0655	0.524	x	X

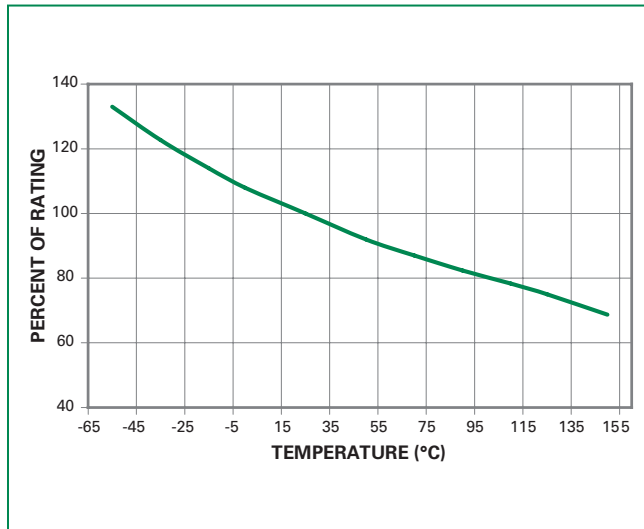
Notes:

- AC Interrupting Rating tested at rated voltage with unity power factor. DC Interrupting Rating tested at rated voltage with time constant < 0.8 msec.
- Nominal Resistance measured with < 10% rated current.
- Nominal Melting I²t measured at 1msec. opening time.
- Nominal Voltage Drop measured at rated current after temperature has stabilized.

Devices designed to carry rated current for 4 hours minimum. It is recommended that devices be operated continuously at no more than 80% rated current. See "Temperature Derating Curve" for additional derating information.

Devices designed to be mounted with marking code facing up.

Temperature Derating Curve



Note:

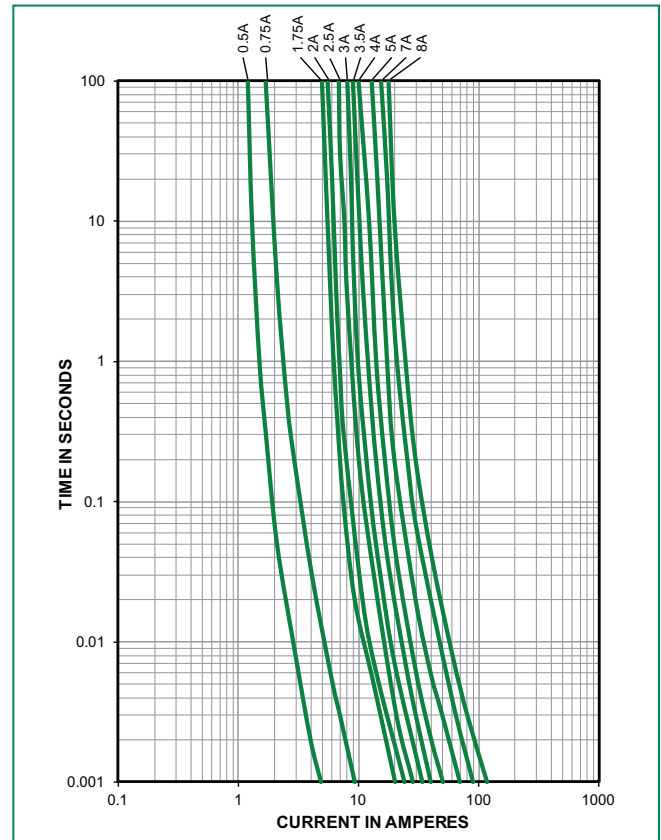
1. Derating depicted in this curve is in addition to the standard derating of 20% for continuous operation.

Example:

For continuous operation at 75 degrees celsius, the fuse should be derated as follows:

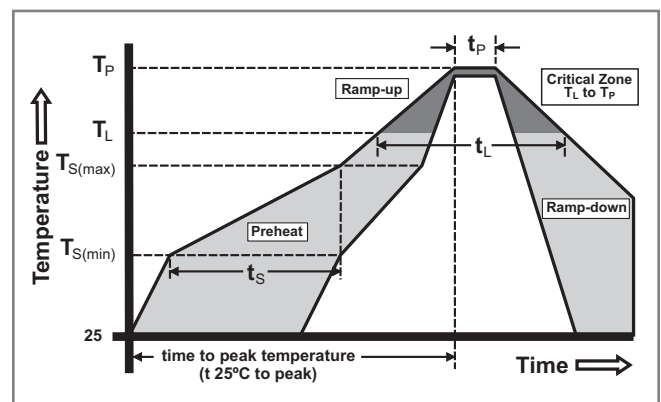
$$I = (0.80)(0.85)I_{\text{RAT}} = (0.68)I_{\text{RAT}}$$

Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb-free assembly
Pre Heat	- Temperature Min ($T_{s(\min)}$)	150°C
	- Temperature Max ($T_{s(\max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 seconds
Average Ramp-Up Rate (Liquidus Temp (T_L) to peak)		3°C/second max.
$T_{s(\max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260±0/5 °C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max.
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C
Wave Soldering		260°C, 10 seconds max.

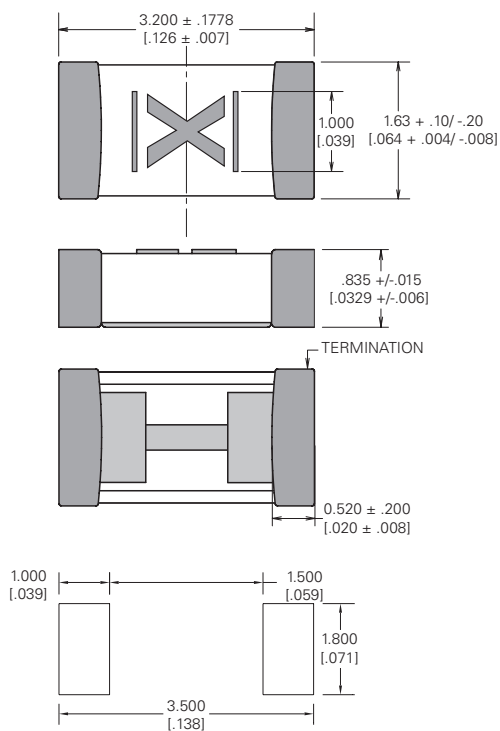


Product Characteristics

Materials	Body: Advanced Ceramic Terminations: Ag / Ni / Sn (100% Lead-free) Element Cover Coating: Lead-free Glass
Moisture Sensitivity Level	IPC/JEDEC J-STD-020, Level 1
Solderability	IPC/ECA/JEDEC J-STD-002, Condition C
Humidity Test	MIL-STD-202, Method 103, Conditions D
Resistance to Solder Heat	MIL-STD-202, Method 210, Condition B
Moisture Resistance	MIL-STD-202, Method 106
Thermal Shock	MIL-STD-202, Method 107, Condition B
Mechanical Shock	MIL-STD-202, Method 213, Condition A
Vibration	MIL-STD-202, Method 201
Vibration, High Frequency	MIL-STD-202, Method 204, Condition D
Dissolution of Metallization	IPC/ECA/JEDEC J-STD-002, Condition D
Terminal Strength	IEC 60127-4

High Temperature Storage	MIL-STD-202, Method 108 with exemptions
Thermal Shock Test	JESD22 Method JA-104, Test Conditions B and N
Biased Humidity	MIL-STD-202, Method 103, 85C/85% RH with 10% operating power for 1000 hrs
Operational Life	MIL-STD-202, Method 108, Test Condition D
Resistance to Solvents	MIL-STD-202, Method 215
Mechanical Shock	MIL-STD-202, Method 213, Test Condition C
High Frequency Vibration	MIL-STD-202, Method 204
Resistance to Soldering Heat	MIL-STD-202, Method 210, Test Condition B
Solderability	JESD22-B102E Method 1
Terminal Strength for SMD	AEC Q200-006
Board Flex	AEC Q200-005
Electrical Characterization	3 Temperature Electrical

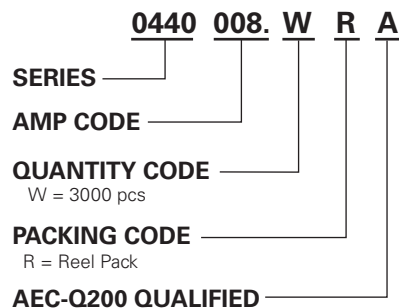
Dimensions



Part Marking System

Amp Code	Marking Code
.500	F
.750	G
1.75	L
002.	N
02.5	O
003.	P
03.5	R
004.	S
005.	T
007.	W
008.	X

Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity and Packaging Code
8mm Tape and Reel	EIA-481, IEC 60286, Part 3	3000	WRA